

$G_{\text{FS}} = 8 \text{ mS/V}$        $V_{\text{GS}} = \pm 20 \text{ V}$        $D = 0.5$

P-Channel Enhancement Mode Field Effect Transistor in a PDFN3x3A-8L Plastic Package.

$V_{\text{DS}} (\text{V}) = -30 \text{ V}$

$I_{\text{D}} = -34 \text{ A}$  ( $V_{\text{GS}} = \pm 20 \text{ V}$ )

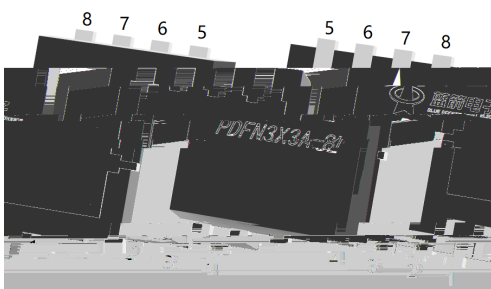
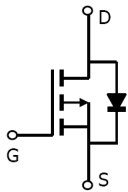
$R_{\text{DS(ON)}} @ 10 \text{ V} = 14 \text{ m}\Omega$  (Typ. 12.8 m $\Omega$ )

$\theta_{\text{JA}} = 100 \text{ } ^\circ\text{C/W}$        $\theta_{\text{JC}} = 10 \text{ } ^\circ\text{C/W}$

HF Product.

Qualified to AEC-Q101 Standards for High Reliability,

These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies, Meet the stringent requirements of automotive applications.

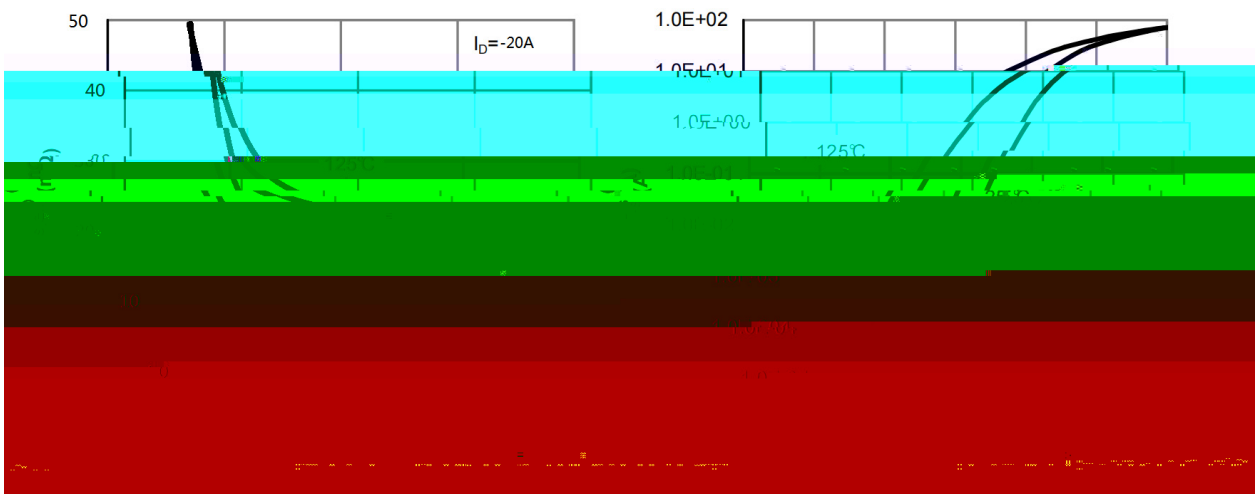
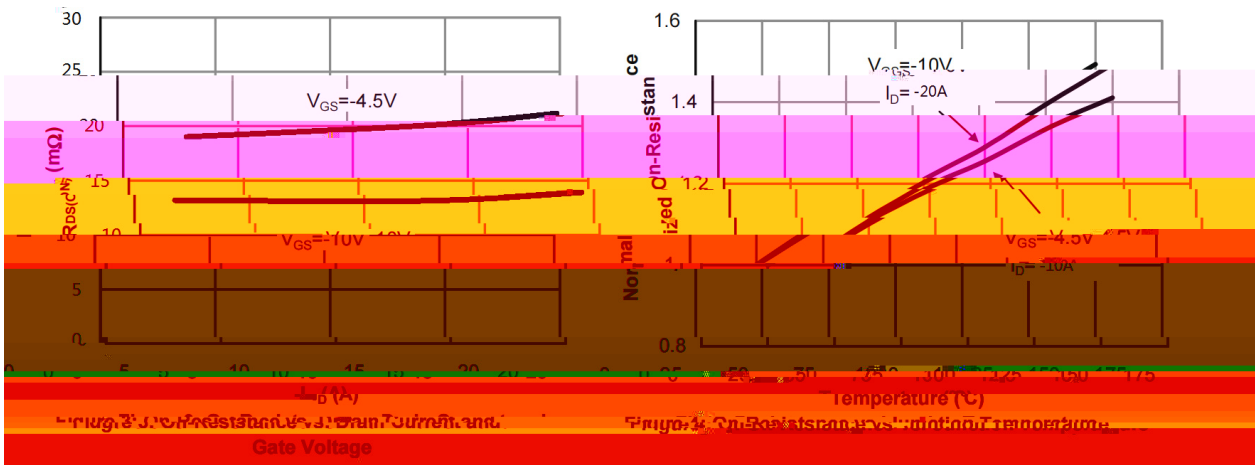
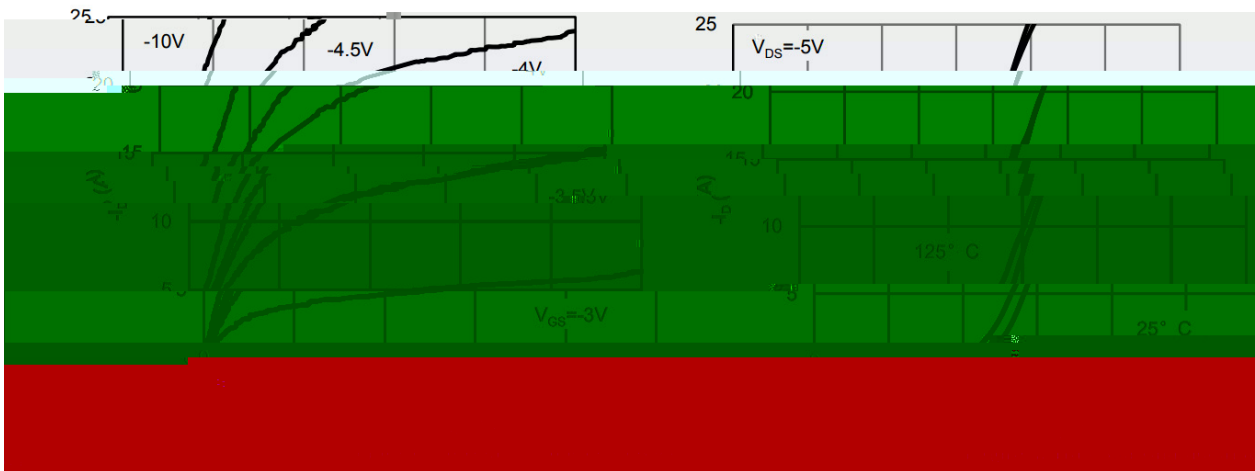


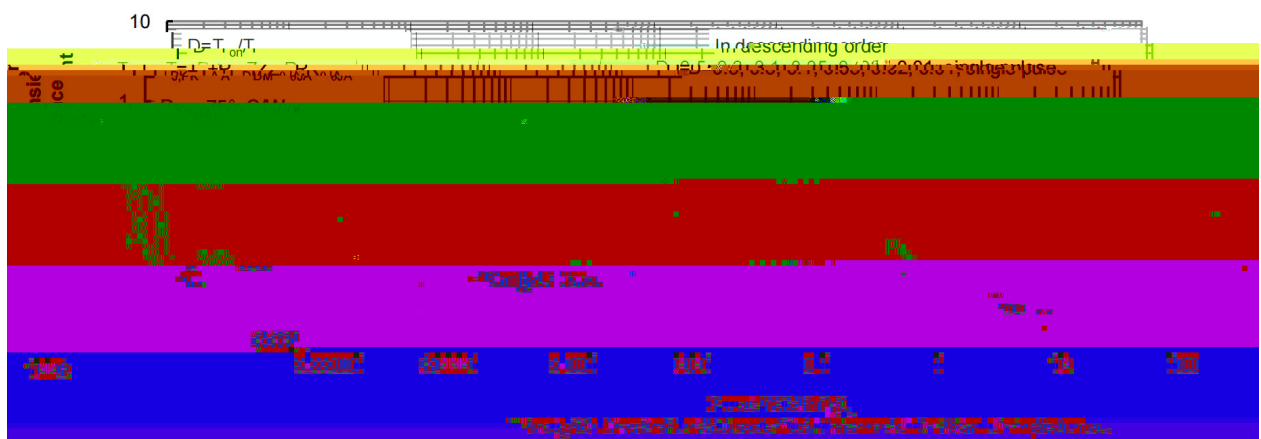
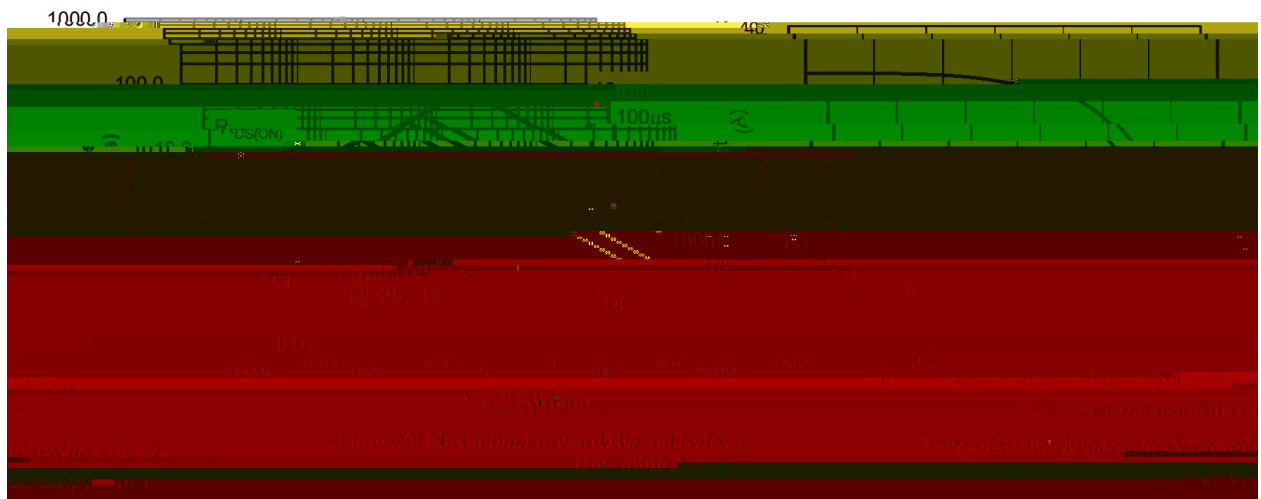
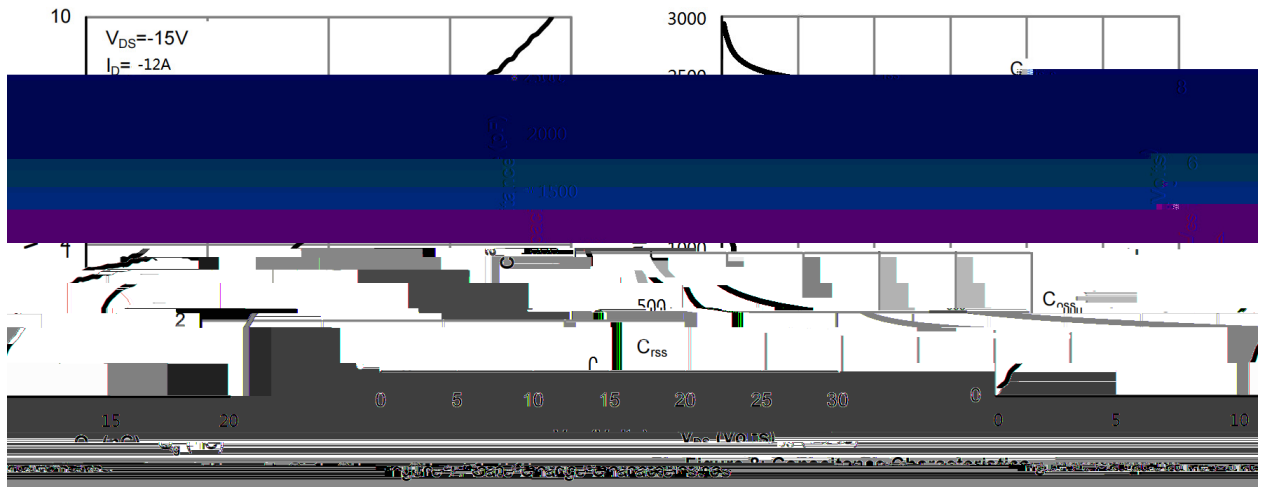
出脚	定义
Pin1	S
Pin2	C
Pin3	S
Pin4	S
Pin5	S
Pin6	S
Pin7	S
Pin8	S

See Marking Instructions.

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DSS}$	-30	V
Drain Current		$I_D(T_C=25^\circ\text{C})$	-34	A
Drain Current - Pulsed		$I_{DM}$	-80	A
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Single Pulsed Avalanche Energy		$E_{AS}$	210	mJ
Avalanche Current		$I_{AS}$	-20	A
Power Dissipation		$P_D(T_C=25^\circ\text{C})$	29	W
Operating and Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	
Junction-to-Ambient	$t = 10$	$R_{JA}$	40	/W
Junction-to-Ambient	Steady-State		75	
Junction-to-Case	Steady-State	$R_{JC}$	4.2	

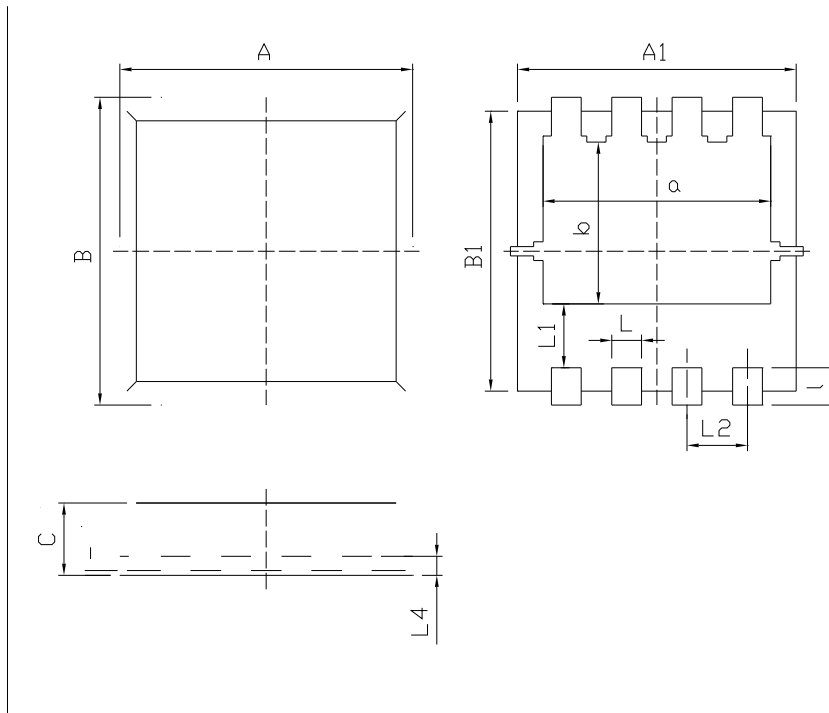
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=-250\text{ A}$ $V_{GS}=0V$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-30V$				





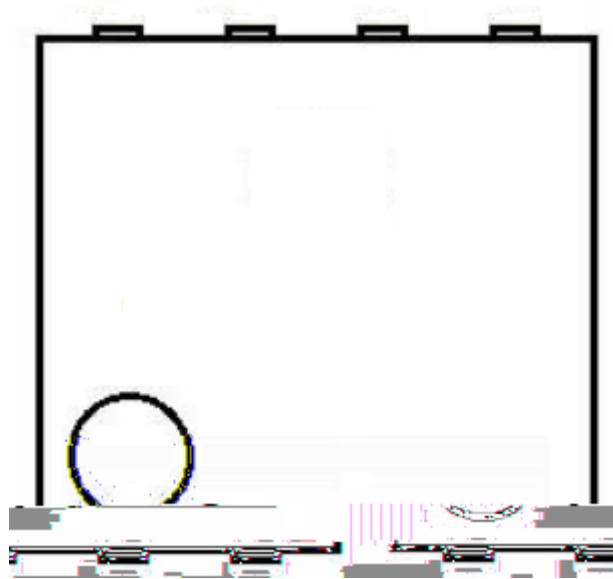
## PDFN3X3A-8L

Unit:mm



Dimensions In Millimeterer			
Symbol	MIN	TYP	MAX
A	3.20	3.30	3.40
A1	3.10	3.15	3.20
B	3.20	3.30	3.40
B1	2.95	3.00	3.05
C	0.75	0.80	0.85
L	0.25	0.30	0.35
L1	-	-	0.75
L2	0.55	0.65	0.75
L4	0.14	0.15	0.20
a	2.35	2.45	2.55
b	1.635	1.735	1.835
k	0.00	-	0.05
l	0.30	0.40	0.50

Rev.00 202011



BR

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Note:

BR:

### Temperature Profile for IR Reflow Soldering(Pb-Free)


**Note:**

- |   |        |     |            |         |   |
|---|--------|-----|------------|---------|---|
| 1 | 150    | 200 | 60         | 120sec; | 1.Preheating:150~200 , Time:60~120sec.    |
| 2 | 255..5 |     | 5..0.5sec; |         | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 |        | 2   | 10         | /sec.   | 3. Cooling Speed: 2~10 /sec.              |

260..5	10..1 sec.	Temp.:260±5	Time:10±1 sec
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/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box